ABSTRACT OF THE DISCLOSURE

LEAD FRAME FOR LOC AND SEMICONDUCTOR DEVICE USING THE SAME

A lead frame for LOC is provided which, even when an adhesive is applied to a lead prepared by stamping, can ensure insulation of a semiconductor element mounted from the lead. In applying an adhesive to a predetermined position of an inner lead 1 in a lead frame prepared by stamping to form an adhesive layer 4, the adhesive layer 4 is provided on the droop face of the inner lead 1. The droop face has no burr and a bulged center portion, permitting contact, derived from the burr, between a lead face and a semiconductor element, to be avoided, which ensures satisfactory insulation of the semiconductor element mounted from the lead.

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